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### **MSA-0436** Cascadable Silicon Bipolar MMIC Amplifiers



### **Data Sheet**

#### Description

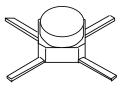
The MSA-0436 is a high performance silicon bipolar Monolithic Microwave Integrated Circuit (MMIC) housed in a cost effective, microstrip package. This MMIC is designed for use as a general purpose 50 $\Omega$  gain block. Typical applications include narrow and broad band IF and RF amplifiers in industrial and military applications.

The MSA-series is fabricated using Avago's 10 GHz  $f_{T}, 25~{\rm GHz}~f_{MAX},$  silicon bipolar MMIC process which uses nitride self-alignment, ion implantation, and gold metallization to achieve excellent performance, uniformity and reliability. The use of an external bias resistor for temperature and current stability also allows bias flexibility.

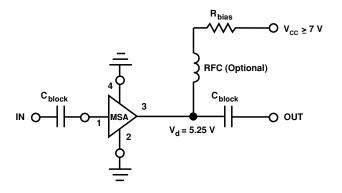
#### Features

- Cascadable 50  $\Omega$  Gain Block
- 3 dB Bandwidth: DC to 3.8 GHz
- \* 12.5 dBm Typical  $P_{1 dB}$  at 1.0 GHz
- 8.5 dB Typical Gain at 1.0 GHz
- Unconditionally Stable (k>1)
- Cost Effective Ceramic Microstrip Package

#### 36 micro-X Package



#### **Typical Biasing Configuration**



#### **MSA-0436 Absolute Maximum Ratings**

Parameter	Absolute Maximum <sup>[1]</sup>				
Device Current	100 mA				
Power Dissipation <sup>[2,3]</sup>	650 mW				
RF Input Power	+13 dBm				
Junction Temperature	150°C				
Storage Temperature <sup>[4]</sup>	-65 to 150°C				

Thermal Resistance<sup>[2,5]</sup>:  $\theta_{\rm jc} = 140^{\circ}{\rm C/W}$ 

#### Notes:

- 1. Permanent damage may occur if any of these limits are exceeded.
- 2.  $T_{CASE} = 25^{\circ}C.$ 3. Derate at 7.1 mW/°C for  $T_C > 109^{\circ}C.$
- 4. Storage above +150°C may tarnish the leads of this package making it difficult to solder into a circuit.
- 5. The small spot size of this technique results in a higher, though more accurate determination of  $q_{jc}$  than do alternate methods.

#### Electrical Specifications^{[1]}, $\rm T_{A}=25^{\circ}C$

Symbol	Parameters and Test Conditions:	Units	Min.	Тур.	Max.	
GP	Power Gain $( S_{21} ^2)$	f = 0.1  GHz	dB	7.5	8.5	9.5
$\Delta G_P$	Gain Flatness	f = 0.1 to 2.5 GHz	dB		±0.6	±1.0
$f_{3 dB}$	3 dB Bandwidth		GHz		3.8	
VSWR	Input VSWR	f = 0.1  to  2.5  GHz			1.4:1	
VSWK	Output VSWR	f = 0.1  to  2.5  GHz			1.9:1	
NF	50 $\Omega$ Noise Figure	f = 1.0  GHz	dB		6.5	
P <sub>1 dB</sub>	Output Power at 1 dB Gain Compression	f = 1.0  GHz	dBm		12.5	
IP <sub>3</sub>	Third Order Intercept Point	f = 1.0  GHz	dBm		25.5	
tD	Group Delay	f = 1.0  GHz	psec		125	
Vd	Device Voltage		V	4.75	5.25	5.75
dV/dT	Device Voltage Temperature Coefficient		mV/°C		-8.0	

Note:

1. The recommended operating current range for this device is 30 to 70 mA. Typical performance as a function of current is on the following page.

#### **Ordering Information**

Part Numbers	No. of Devices	Comments		
MSA-0436-BLKG	100	Bulk		
MSA-0436-TR1G	1000	7" Reel		

 $\mathbf{2}$ 

Freq.	<b>S</b> <sub>11</sub>		<b>S</b> <sub>21</sub>			S <sub>12</sub>			$\mathbf{S}_{22}$	
GHz	Mag	Ang	dB	Mag	Ang	dB	Mag	Ang	Mag	Ang
0.1	.08	175	8.5	2.67	175	-16.4	.151	1	.20	-10
0.2	.08	172	8.5	2.68	170	-16.3	.153	2	.20	-16
0.4	.07	171	8.5	2.67	161	-16.4	.151	3	.20	-33
0.6	.07	166	8.5	2.66	151	-16.2	.155	6	.21	-45
0.8	.05	169	8.4	2.64	142	-16.1	.156	8	.22	-57
1.0	.05	175	8.3	2.61	136	-16.0	.159	10	.24	-68
1.5	.04	-142	8.1	2.55	109	-15.0	.178	13	.26	-96
2.0	.09	-145	7.8	2.46	87	-14.2	.196	15	.28	-123
2.5	.14	-154	7.3	2.33	71	-13.1	.221	18	.31	-140
3.0	.22	-175	6.6	2.14	50	-12.5	.238	14	.33	-160
3.5	.28	170	5.8	1.94	32	-11.7	.260	9	.35	-173
4.0	.34	156	4.8	1.74	15	-11.3	.271	4	.34	-179
4.5	.37	140	3.9	1.57	-1	-10.7	.291	-2	.33	-171
5.0	.42	120	3.0	1.41	-16	-10.4	.302	-8	.32	-160

MSA-0436 Typical Scattering Parameters (Z $_{\rm 0}$  = 50  $\Omega,$  T $_{\rm A}$  = 25°C, I $_{\rm d}$  = 50 mA)

# **Typical Performance**, **T**<sub>A</sub> **= 25°C** (unless otherwise noted)

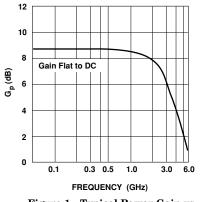


Figure 1. Typical Power Gain vs. Frequency,  $T_A$  = 25°C,  $I_d$  = 50 mA.

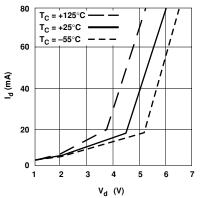


Figure 2. Device Current vs. Voltage.

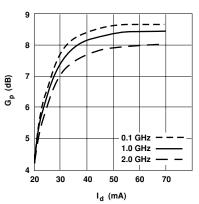


Figure 3. Power Gain vs. Current.

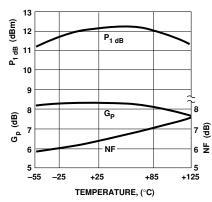


Figure 4. Output Power at 1 dB Gain Compression, NF and Power Gain vs. Case Temperature, f = 1.0 GHz,  $I_d = 50 \text{ mA}.$ 

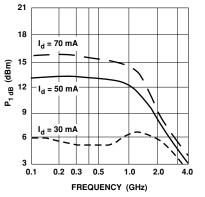
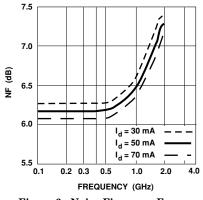
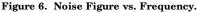
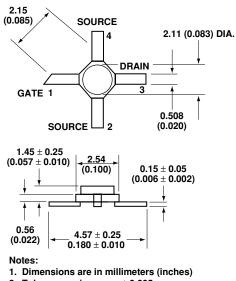


Figure 5. Output Power at 1 dB Gain **Compression vs. Frequency.** 





#### 36 micro-X Package Dimensions



2. Tolerances: in .xxx =  $\pm$  0.005 mm .xx =  $\pm$  0.13

For product information and a complete list of distributors, please go to our web site: www.avagotech.com

